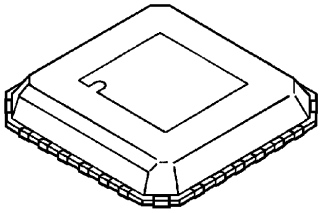
TOSHIBA BIPOLAR LINEAR IC SILICON MONOLITHIC

TA2131FL

LOW CURRENT CONSUMPTION HEADPHONE AMPLIFIER FOR PORTABLE MD PLAYER (WITH BASS BOOST FUNCTION)

The TA2131FL is a low current consumption headphone amplifier developed for portable digital audio. It is particularly well suited to portable MD players that are driven by a single dry cell. It also features a built-in bass boost function with AGC, and is capable of bass amplification of DAC output and analog signals such as tuner.
An ultra-compact QON package is utilized, enabling sets to be compacted.



QON24-P-0505-0.50

Weight : 0.05 g (Typ.)

Actual product display name : 2131

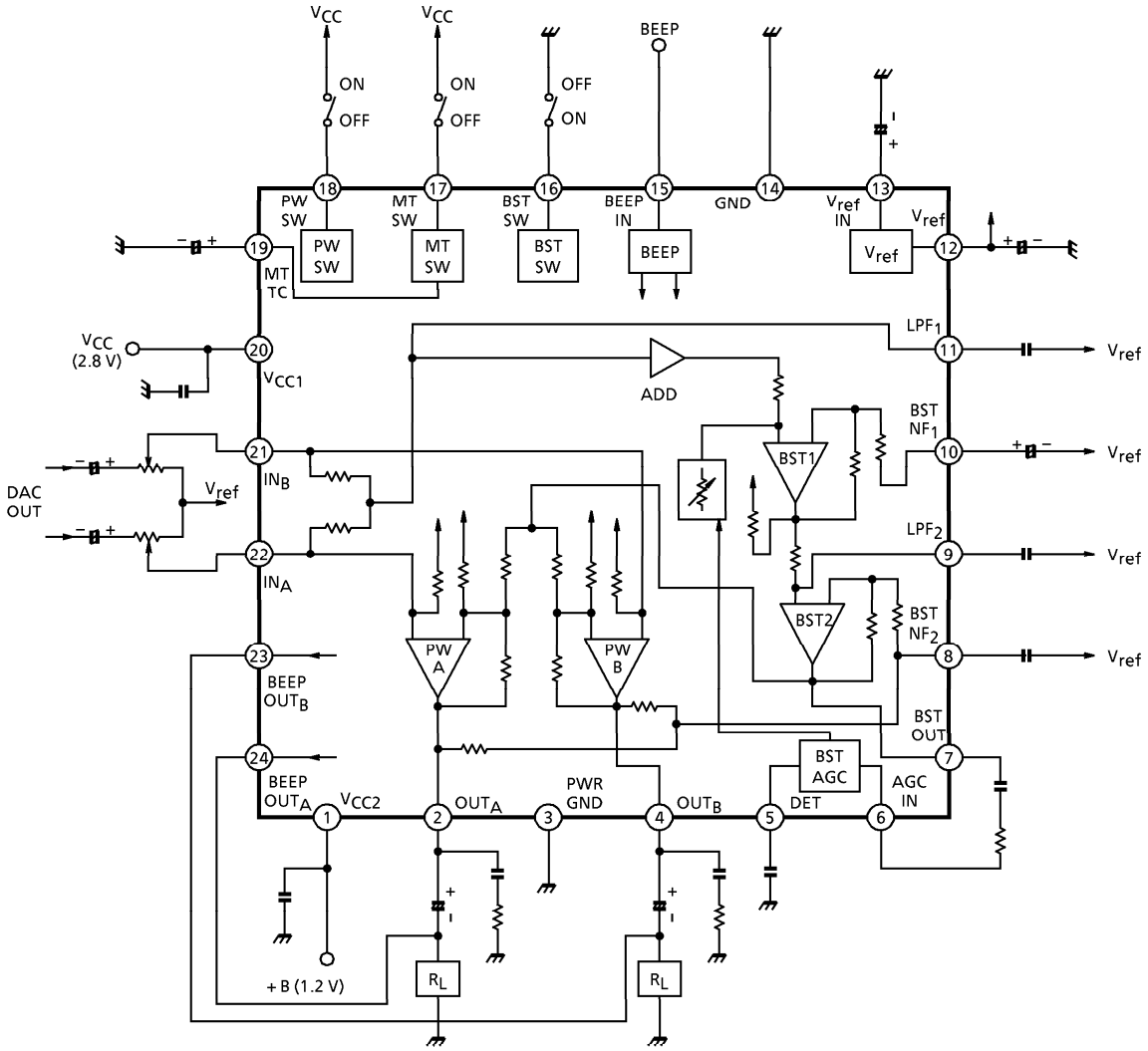
FEATURES

- Low current consumption : I_{CCQ} (V_{CC1}) = 0.55 mA (Typ.)
  I_{CCQ} (V_{CC2}) = 0.20 mA (Typ.)
- Output power : P_O = 8 mW (Typ.)
  (V_{CC1} = 2.8 V, V_{CC2} = 1.2 V, f = 1 kHz, THD = 10%, R_L = 16 Ω)
- Low noise : V_{no} = − 102 dBV (Typ.)
- Built-in low-pass boost (with AGC)
- I/O pin for beep sound
- Outstanding ripple rejection ratio
- Built-in power mute
- Built-in power ON/OFF switch
- Operating supply voltage range (Ta = 25°C) : V_{CC1} = 1.8~4.5 V
  V_{CC2} = 0.9~4.5 V

980910EBA1

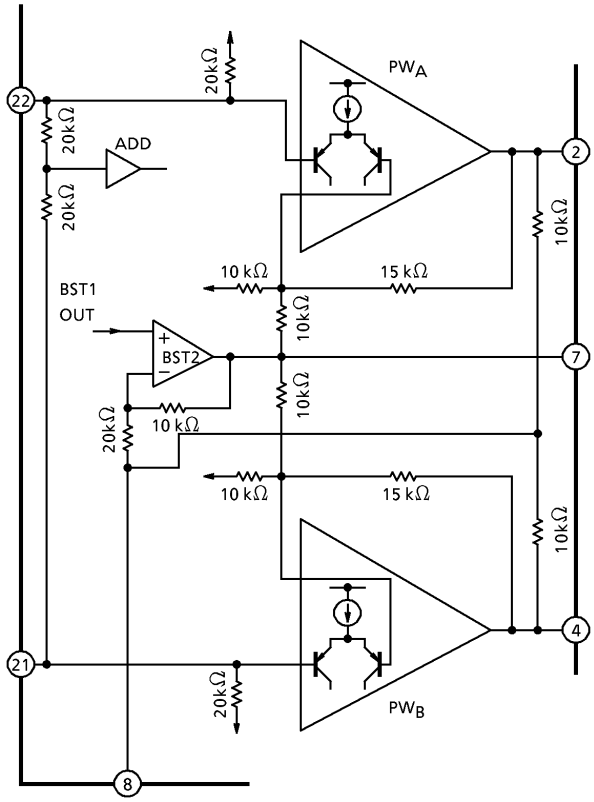
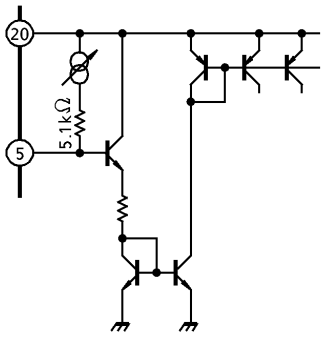
- TOSHIBA is continually working to improve the quality and the reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to observe standards of safety, and to avoid situations in which a malfunction or failure of a TOSHIBA product could cause loss of human life, bodily injury or damage to property. In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent products specifications. Also, please keep in mind the precautions and conditions set forth in the TOSHIBA Semiconductor Reliability Handbook.
- The products described in this document are subject to the foreign exchange and foreign trade laws.
- The information contained herein is presented only as a guide for the applications of our products. No responsibility is assumed by TOSHIBA CORPORATION for any infringements of intellectual property or other rights of the third parties which may result from its use. No license is granted by implication or otherwise under any intellectual property or other rights of TOSHIBA CORPORATION or others.
- The information contained herein is subject to change without notice.

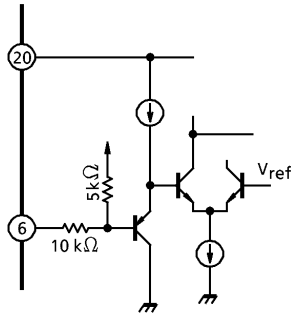
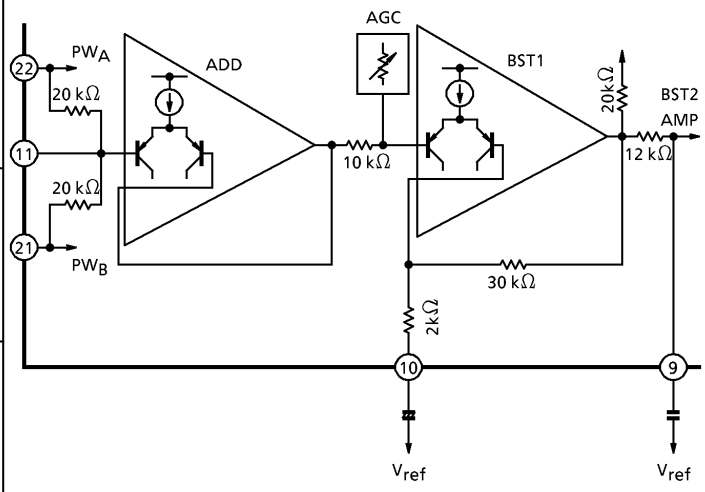
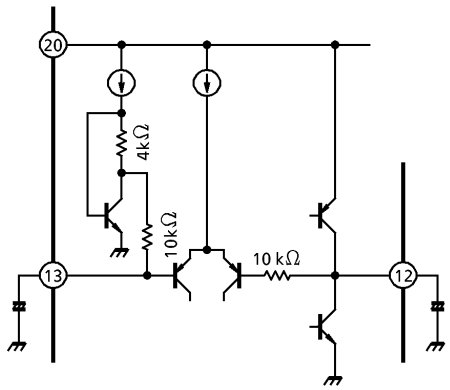
BLOCK DIAGRAM

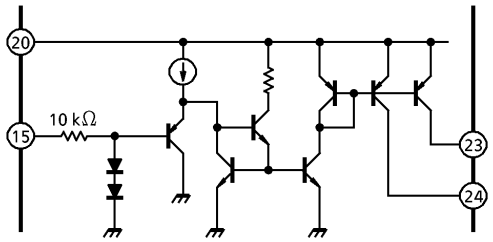
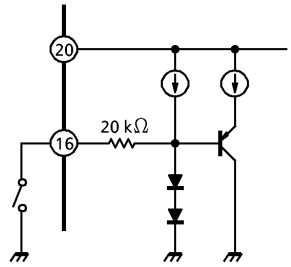
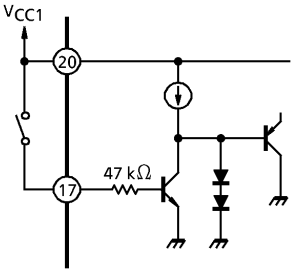
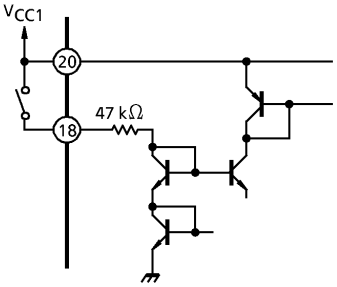


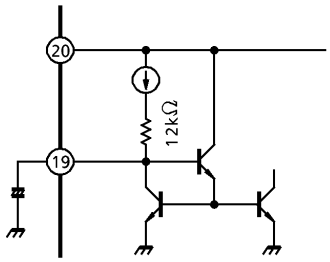
TERMINAL EXPLANATION

(Terminal voltage : Typical terminal voltage at no signal with test circuit, V_{CC1} = 2.8 V, V_{CC2} = 1.2 V, Ta = 25°C)

TERMINAL No.		TERMINAL EXPLANATION	INTERNAL CIRCUIT	TERMINAL VOLTAGE (V)
1	V_{CC2}	V_{CC} (+B) at power amplifier output stage	—	1.2
2	OUT_A	Power amplifier output		0.61
4	OUT_B			
21	IN_B	Power amplifier input		0.61
22	IN_A			
7	BST OUT	BST amplifier 2 output terminal		0.61
8	BST NF_2	BST amplifier 2 NF terminal (low-pass compensation condenser connection terminal)		0.61
3	PWR GND	GND of power amplifier output stage	—	0
5	DET	Smoothing of boost AGC level detection		—

TERMINAL No.		TERMINAL EXPLANATION	INTERNAL CIRCUIT	TERMINAL VOLTAGE (V)
6	AGC IN	Signal input level to BST amplifier is varied according to the input level to the boost AGC input terminal. Input impedance : 15 kΩ (typ.)		0.61
9	LPF_2	BST amplifier 1 output (filter terminal)		0.61
10	BST NF_1	BST amplifier 1 NF		0.61
11	LPF_1	ADD amplifier output (filter terminal)		0.61
12	V_{ref}	Reference voltage circuit		0.61
13	V_{ref} IN	Reference voltage circuit filter terminal		0.61
14	GND	GND of input stage in power amplifier	—	0

TERMINAL No.		TERMINAL EXPLANATION	INTERNAL CIRCUIT	TERMINAL VOLTAGE (V)
15	BEEP IN	Beep sound input terminal Receives beep sound signals from microcomputer.		0
23	BEEP OUT_B	Beep sound output terminal		—
24	BEEP OUT_A			
16	BST SW	Bass boost ON / OFF switch OPEN / V_{CC} : BST ON GND : BST OFF		—
17	MT SW	Mute switch GND / OPEN : mute reset V_{CC} : mute ON		—
18	PW SW	Power ON / OFF switch V_{CC} : IC operation GND / OPEN : IC OFF		—

TERMINAL No.		TERMINAL EXPLANATION	INTERNAL CIRCUIT	TERMINAL VOLTAGE (V)
19	MT TC	Mute smoothing Power mute switch Reduces the shock noise during switching		1.2
20	V_{CC1}	Main V_{CC}	—	2.8

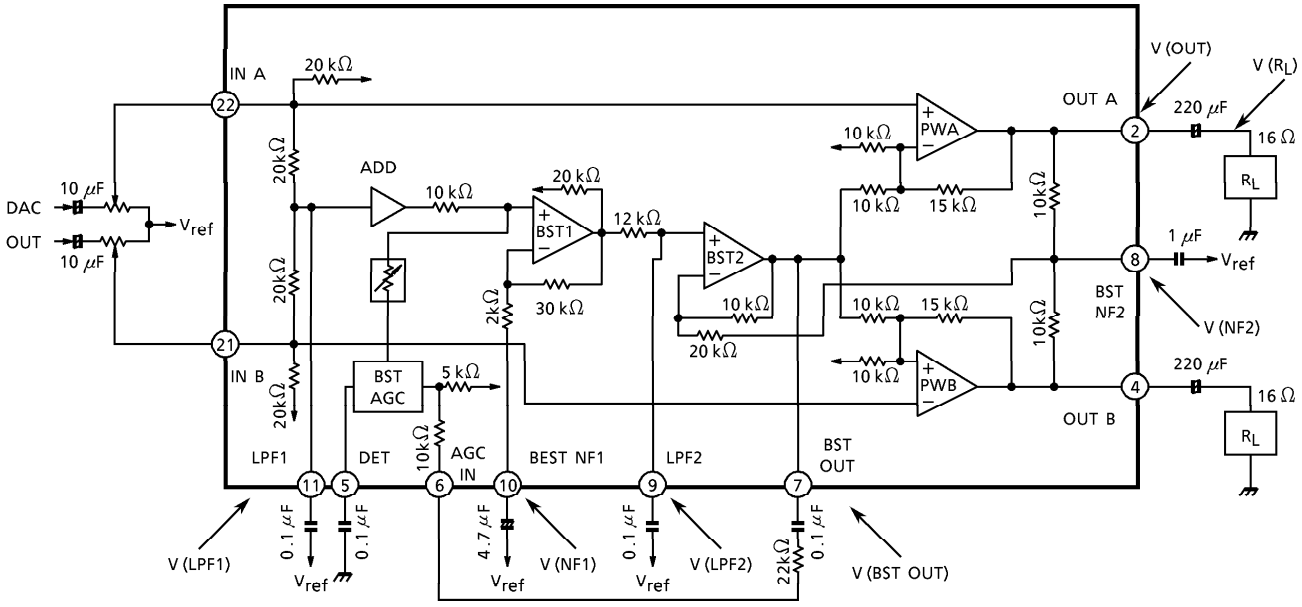
FUNCTION EXPLANATION

1. Bass Boost Function

   a. Description of Operation

   TA2131FL has a bass boost function for bass sound reproduction built-in to the power amplifier. With the bass boost function, at medium levels and lower, channel A and channel B are added for the low frequency component, and output to BST amplifier 2 (BST2) in negative phase. That signal is inverted and added before being subjected to bass boost. If the signal of the low-frequency component reaches a high level, the boost gain is controlled to main a low distortion (see Fig.1).

Fig.1 System Diagram of Bass Boost



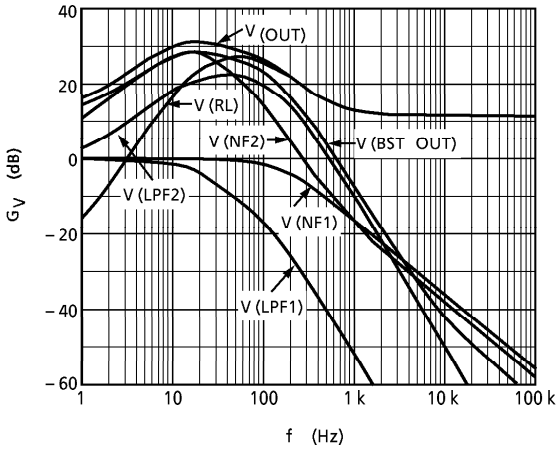
   b. AGC Circuit

   The AGC circuit of the bass boost function detects with "AGC DET" the voltage component created by "BST2," and as the input level increases, the variable impedance circuit is changed, and the bass boost signal is controlled so that it is not assigned to BST amplifier 1. In this way, the bass signal to "BST2" input is shut-off, and that boost gain is controlled.

   c. Bass Boost System

   As shown in Fig.1, the flow of the bass boost signal is that the signal received from power amplifier input goes through LPF1, ADD amplifier, ATT (variable impedance circuit), BPF1 (BST amplifier 1) and LPF2, and the negative phase signal to the power amplifier input signal is output from BST amplifier 2. The reason why it becomes the negative phase of the BST amplifier 2 signal is that the phase is inverted by 180° in the audible bandwidth by the secondary characteristics of LPF1 and LPF2 in Fig.1.
   Ultimately the main signal and the bass boost signal formed before BST2 are added.
   Fig.2 shows the frequency characteristics to each terminal.

Fig.2 During Bass Boost (Frequency Characteristics to Each Terminal)



2-1. Low-Pass Compensation Function

In C-couple type power amplifiers, it is necessary to give the output condenser C a large capacity to flatten out the frequency characteristics to the low frequency band (this is because the loss in the low frequency bandwidth becomes larger due to the effect of the high-pass filter comprising C and R_L). Particularly when the headphone load is approximately 16 Ω and an attempt is being made to achieve frequency characteristics of ± 3 dB at 20 Hz, a large capacity condenser of C = 470 μF is required.

Bearing this situation in mind, a low-pass compensation function was built in to the TA2131FL, and while reducing the capacity of the output coupling condenser, almost flat (± 3 dB) frequency characteristics in all audible bandwidths (20 Hz to 20 kHz) have been achieved.

Fig.3 shows the low-pass system diagram, and Fig.4 shows the frequency characteristics at each point. In Fig.4, (a) represents the status lost by the low-pass as a result of the high-pass filter comprising the headphone load (R_L = 16 Ω) and the output coupling condenser (220 μF) in the C-coupling system.

Fig.3 Low-Pass Compensation System Diagram

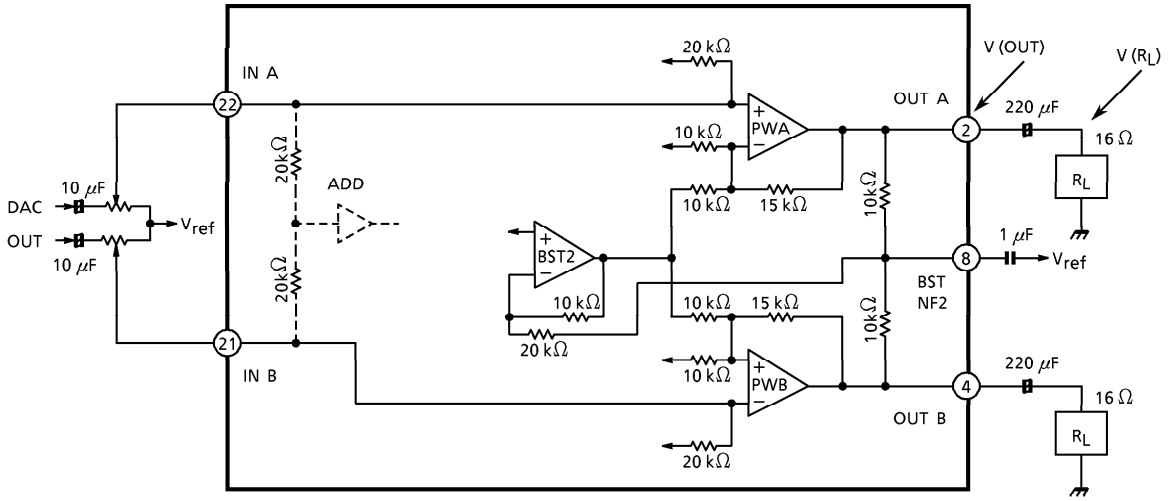
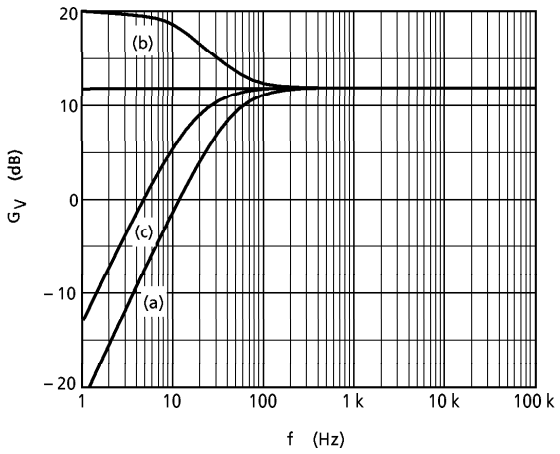


Fig.4 Power Amplifier Frequency Characteristics



<Principle of Low-Pass Compensation>

The low-pass component alone is extracted from the composite signal of PWA / PWB output, and that frequency signal is fed back to PWA / PWB once more via the inversion amplifier, thereby making it possible to increase the gain only of the low-pass component. The frequency characteristics of the power amplifier output $V_{(out)}$ in this state are shown in Fig.4 (b). In practice they are the frequency characteristics (c) viewed from load terminal V (R_L), and the low-pass is compensated relative to the state in (a).

2-2. Low-Pass Compensation Condenser and Crosstalk

In this low-pass compensation condenser circuit, processing is carried out using the composite signal of power amplifier output, so this affects crosstalk, according to the amount of compensation.
f characteristics and crosstalk generated by the capacity of the condenser for compensation (8-pin) are shown below.

Fig.5 Condenser and f Characteristics for Low-Pass Compensation

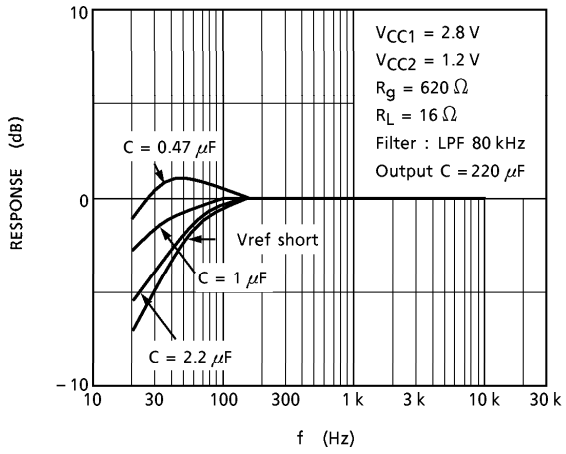
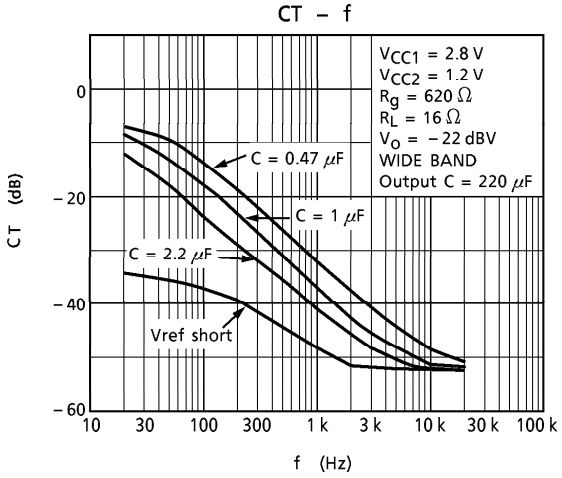
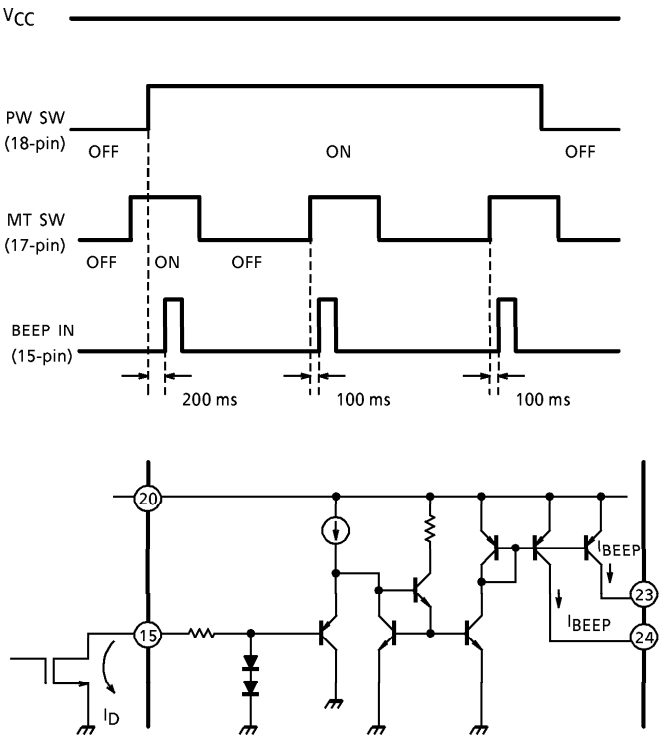


Fig.6 Low-Pass Compensation Condenser and Crosstalk



3. Beep

Beep sound signals from microcomputer can be received by the beep input terminal (15-pin). The PW_A and PW_B of the power amplifier during power mute are turned OFF, and the beep signal input from BEEP-IN (15-pin) is output from the BEEP-OUT terminal (23 / 24-pin) as fixed current, after passing through the converter and current amplification stage. Connecting this terminal to the headphone load outputs the beep sound.
If the beep sound is not input, fix the BEEP-IN (15-pin) terminal to GND level.

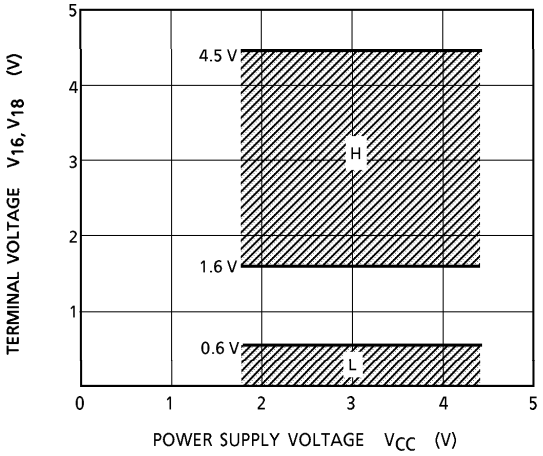


4. Power Switch

As long as the power switch is not connected to V_{CC1}, the IC does not operate. If it malfunctions due to external noise, however, it is recommended to connect a pull-down resistor externally (the power switch is set to be highly sensitive).

5. Threshold Voltages of Switches

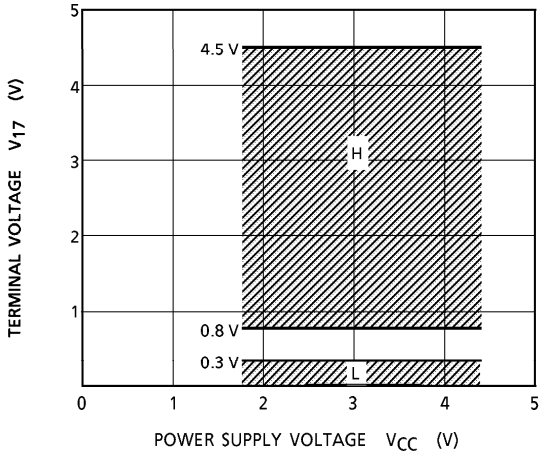
① PW SW, BST SW



	PW SW (V_{18})
'H'	IC operation
'L' OPEN	IC OFF

	BST SW (V_{16})
'H' OPEN	BST ON
'L'	BST OFF

② MT SW



	MT SW (V_{17})
'H'	Mute ON
'L' OPEN	Mute reset

6. These capacitors which prevent oscillation of the power amplifier, and are between the V_{ref} and V_{CC}-GND must have a small temperature coefficient and outstanding frequency characteristics.

MAXIMUM RATINGS

CHARACTERISTIC	SYMBOL	RATING	UNIT
Supply Voltage	V_{CC}	4.5	V
Output Current	$I_{o\,(peak)}$	100	mA
Power Dissipation	P_D (Note)	550	mW
Operating Temperature	T_{opr}	−25~75	°C
Storage Temperature	T_{stg}	−55~150	

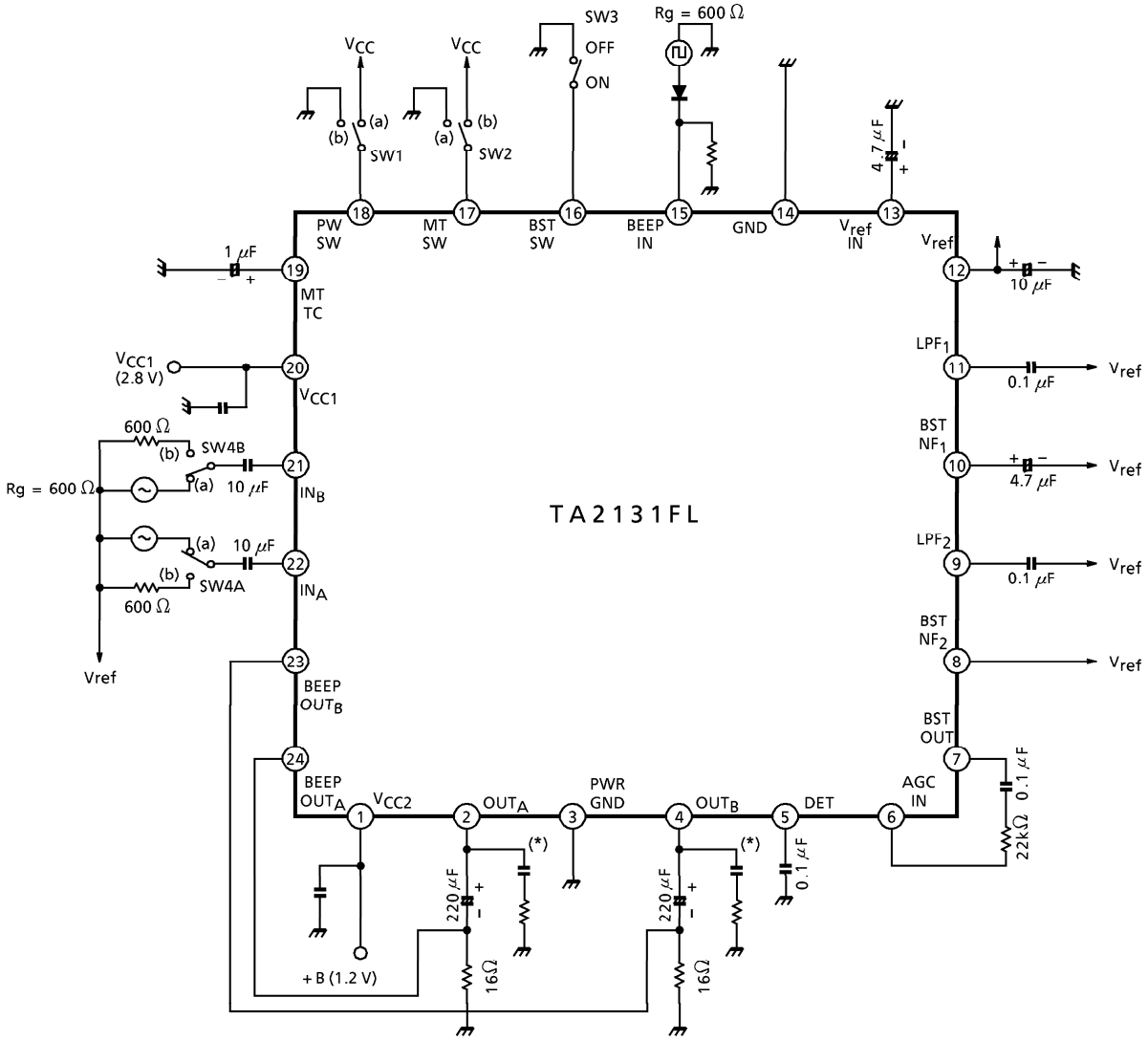
(Note) : Subtract 5.4 mW for each 1°C if used at temperatures greater than 25°C.

ELECTRICAL CHARACTERISTICS

(Unless specified otherwise, V_{CC1} = 2.8 V, V_{CC2} = 1.2 V, R_g = 600 Ω, R_L = 16 Ω, f = 1 kHz, Ta = 25°C)

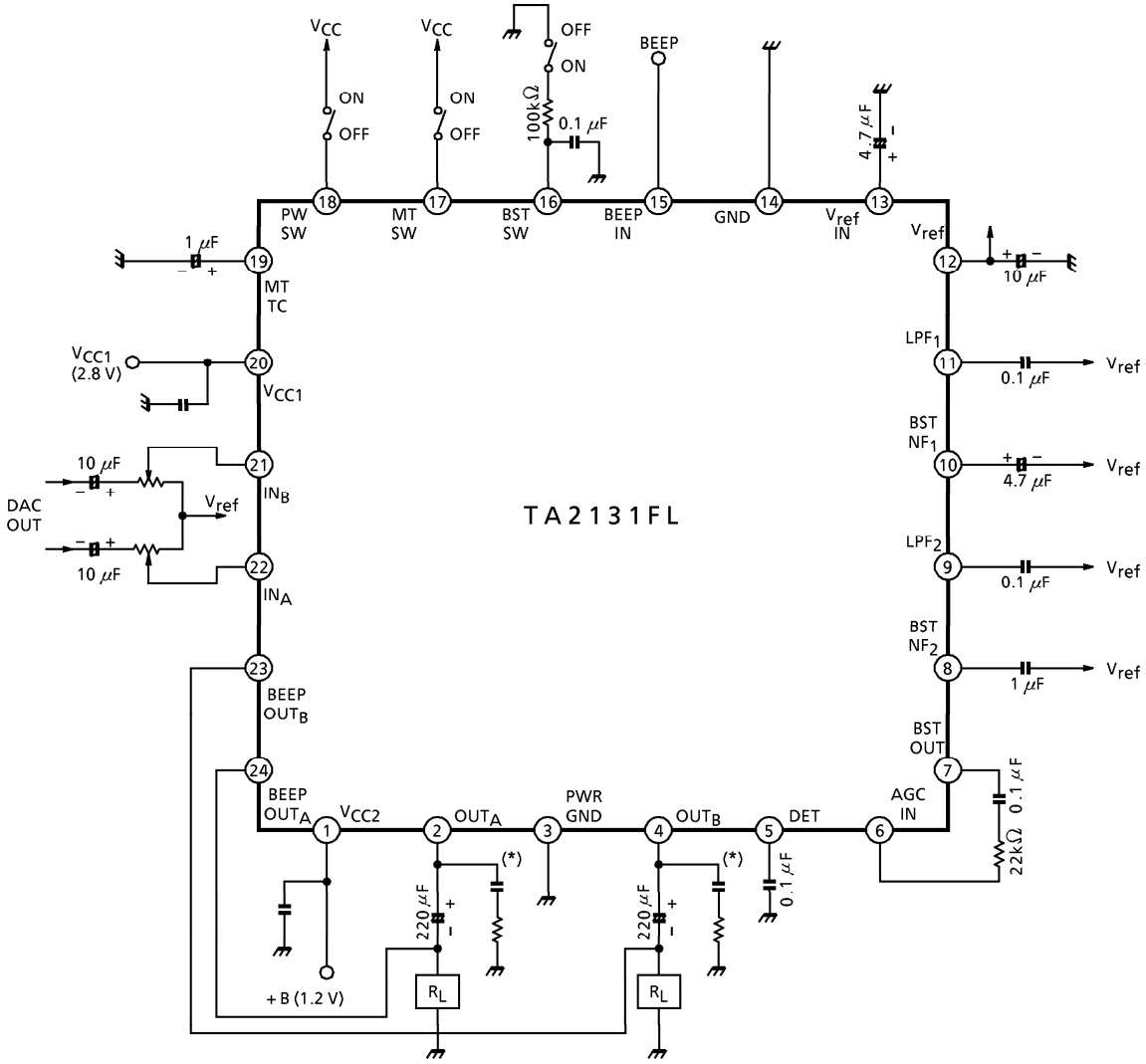
CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Quiescent Supply Current		I_{CC1}	IC OFF (V_{CC1}), SW1 : b, SW2 : b	—	0.1	5	μA
		I_{CC2}	IC OFF (V_{CC2}), SW1 : b, SW2 : b	—	0.1	5	
		I_{CC3}	MUTE ON (V_{CC1}), SW1 : a, SW2 : b	—	0.35	0.50	mA
		I_{CC4}	MUTE ON (V_{CC2}), SW1 : a, SW2 : b	—	5	10	μA
		I_{CC5}	No signal (V_{CC1}), SW1 : a, SW2 : a	—	0.55	0.75	mA
		I_{CC6}	No signal (V_{CC2}), SW1 : a, SW2 : a	—	0.20	0.40	
Power Supply Current During Drive		I_{CC7}	P_O = 0.5 mW + 0.5 mW output (V_{CC1})	—	0.6	—	
		I_{CC8}	P_O = 0.5 mW + 0.5 mW output (V_{CC2})	—	5.3	—	
Power Section	Gain	G_V	V_O = −22 dBV	10	12	14	dB
	Channel Balance	CB	V_O = −22 dBV	−1.5	0	1.5	
	Output Power	P_{omax}	THD = 10%	5	8	—	mW
	Total Harmonic Distortion	THD	P_O = 1 mW	—	0.1	0.3	%
	Output Noise Voltage	V_{no}	R_g = 600 Ω, Filter : IHF-A, SW4 : b	—	−102	−96	dBV
	Crosstalk	CT	V_O = −22 dBV	42	48	—	dB
	Ripple Rejection Ratio	RR1	fr = 100 Hz, Vr = −20 dBV inflow to V_{CC2}	71	77	—	
		RR2	fr = 100 Hz, Vr = −20 dBV inflow to V_{CC1}	54	64	—	
	Mute Attenuation	ATT	V_O = −12 dBV, SW2 : a → b	90	100	—	
	Beep Sound Output Voltage	VBEEP	V Beep IN = 2 $V_{p\text{-}o}$, SW2 : b	−53	−48	−43	dBV
Boost Gain		BST1	V_O = −20 dBV, f = 100 Hz, SW3 : ON → OPEN	1	4	7	dB
		BST2	V_O = −30 dBV, f = 100 Hz, SW3 : ON → OPEN	10	13	16	
		BST3	V_O = −50 dBV, f = 100 Hz, SW3 : ON → OPEN	13.5	16.5	19.5	

TEST CIRCUIT



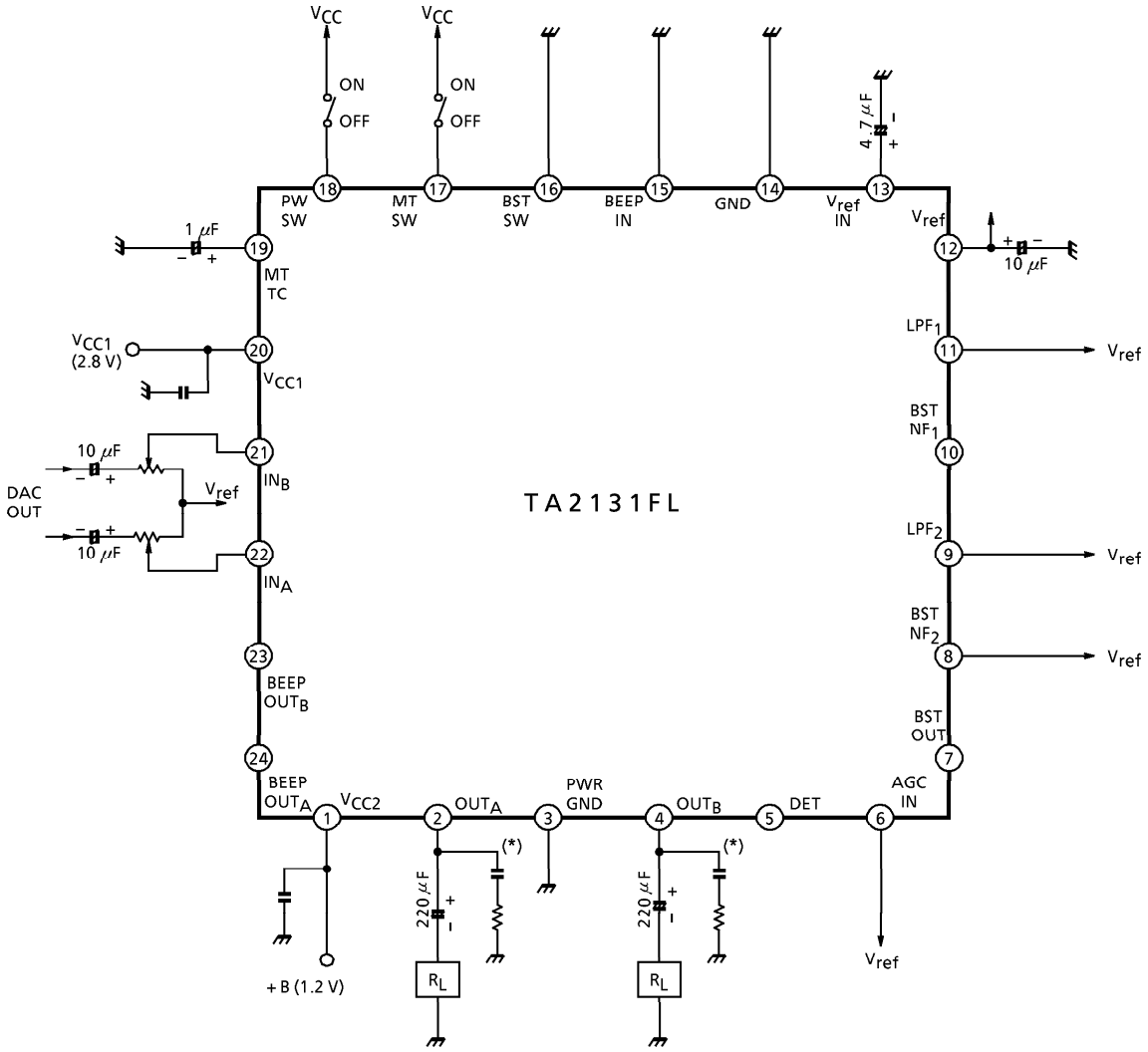
(*) 0.22 μF + 10 Ω
Monolithic ceramic capacitor

APPLICATION CIRCUIT 1



(*) 0.22 μF + 10 Ω
Monolithic ceramic capacitor

APPLICATION CIRCUIT 2 (Low-Pass Compensation / Bass Boost Function / Beep Not Used)

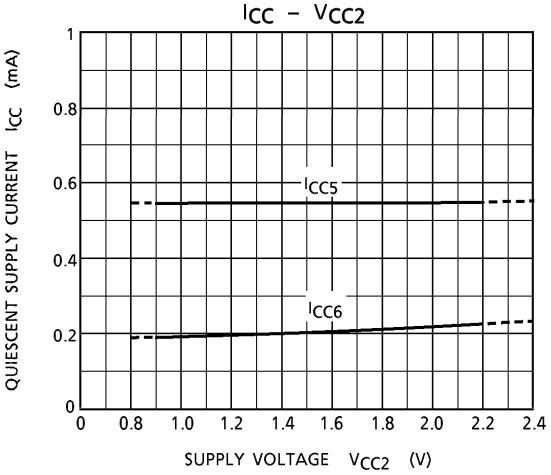


(*) 0.22 μF + 10 Ω
Monolithic ceramic capacitor

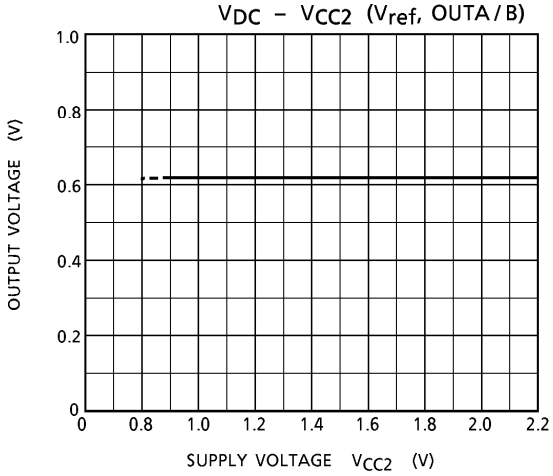
CHARACTERISTICS

(Unless otherwise specified V_{CC1} = 2.8 V, V_{CC2} = 1.2 V, Rg = 600 Ω, R_L = 16 Ω, f = 1 kHz, Ta = 25°C)

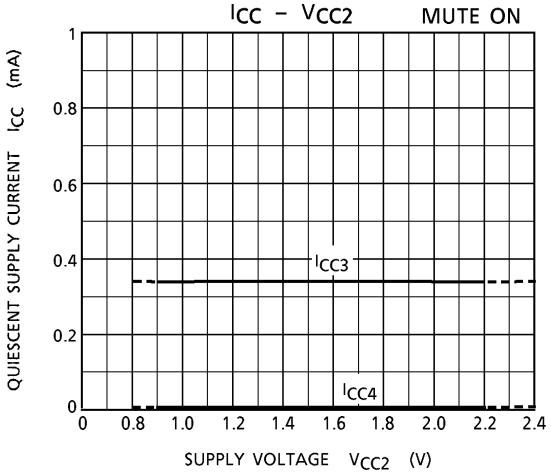
I_{CC} – V_{CC2}



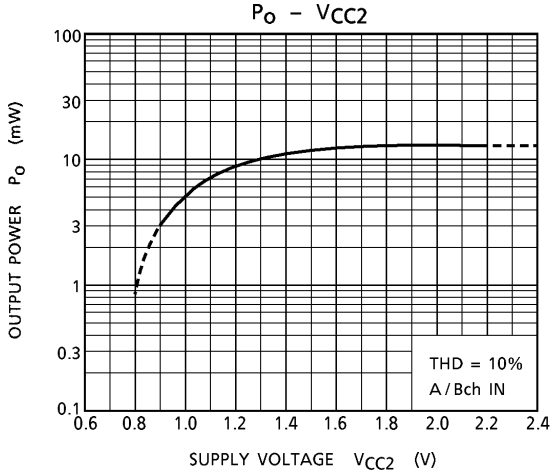
V_{DC} – V_{CC2} (V_{ref}, OUTA/B)



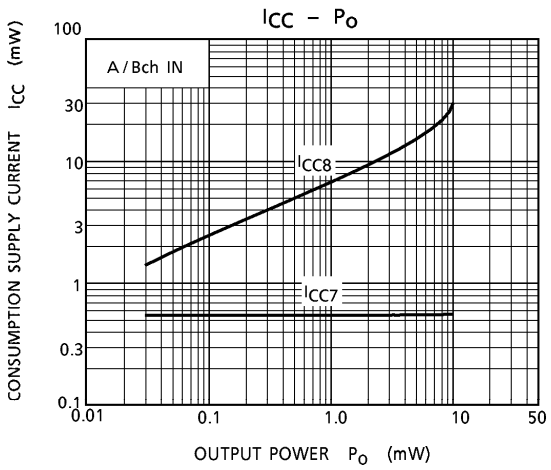
I_{CC} – V_{CC2} MUTE ON



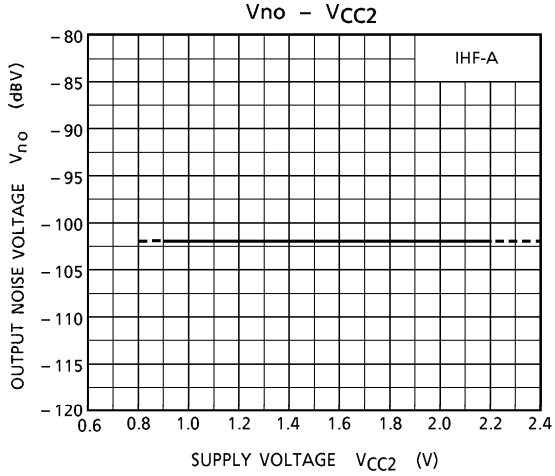
P_O – V_{CC2}



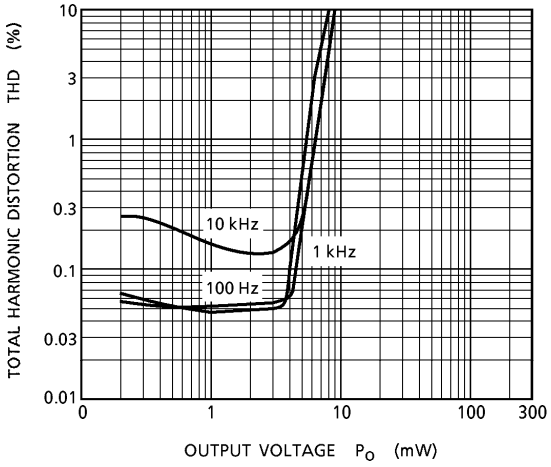
I_{CC} – P_O



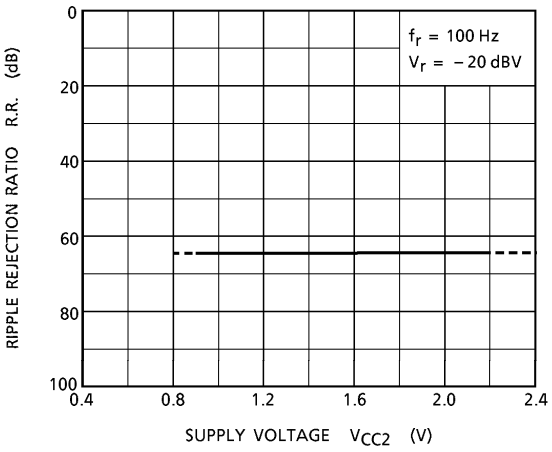
Vno – V_{CC2}



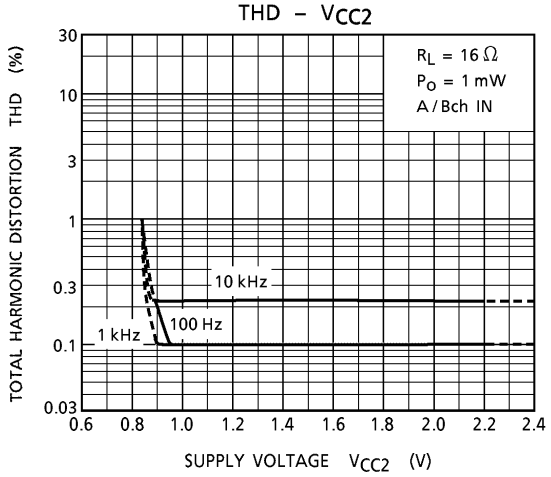
THD – P_O



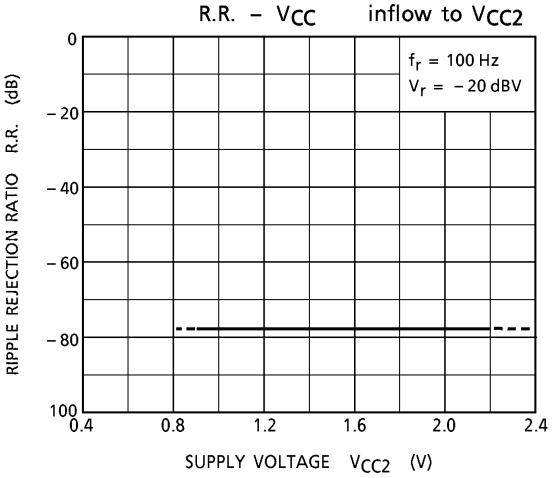
R.R. – V_{CC2} inflow to V_{CC1}



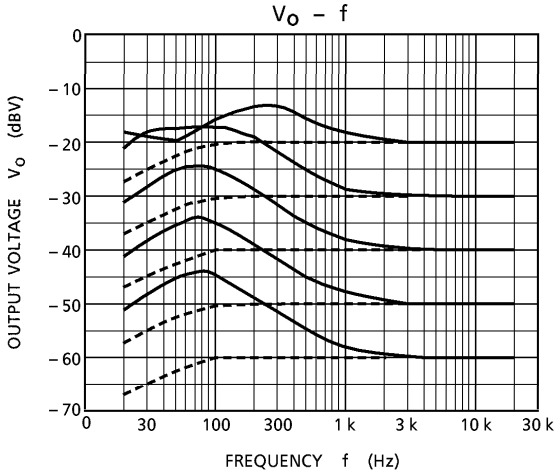
THD – V_{CC2}



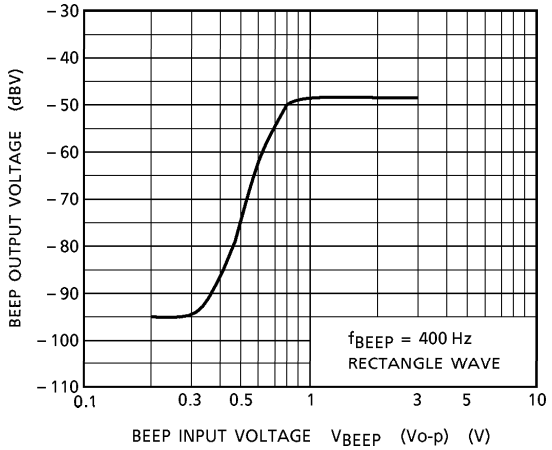
R.R. – V_{CC} inflow to V_{CC2}



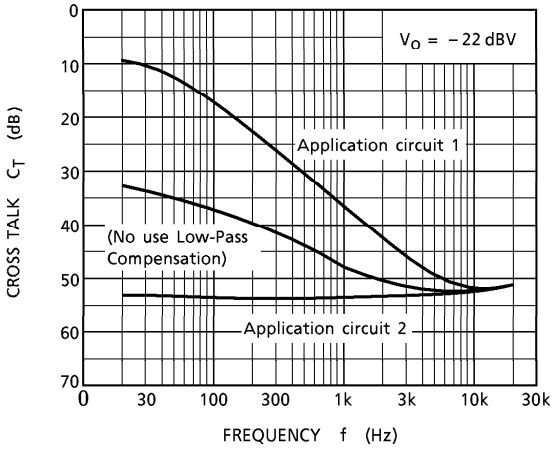
V_O – f



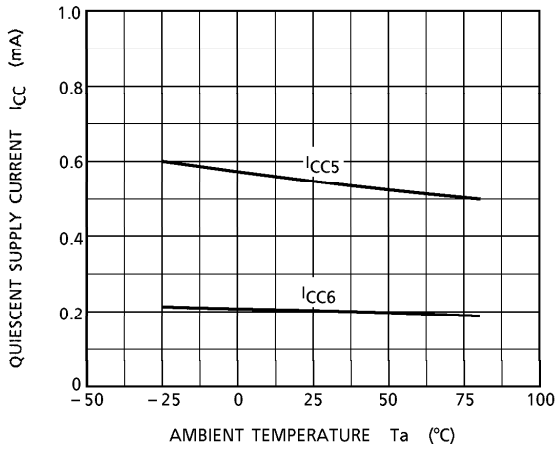
BEEP



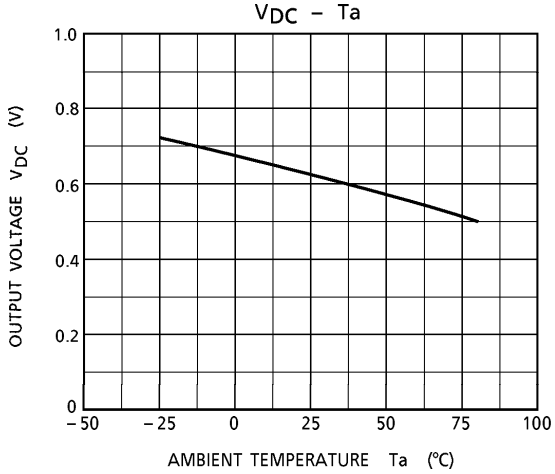
C_T – f



I_{CC} – Ta

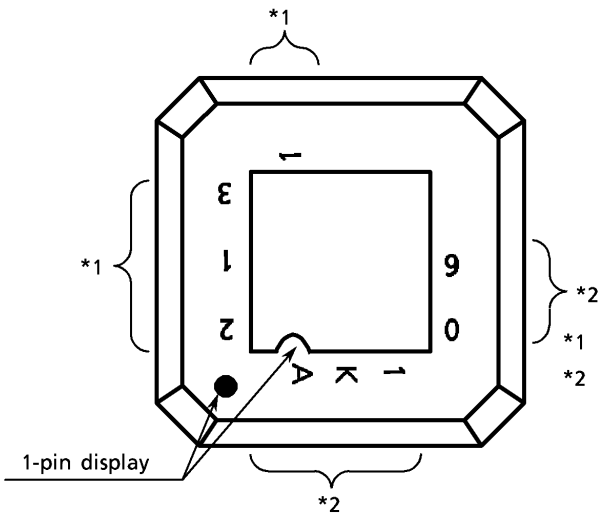


V_{DC} – Ta



DISPLAY OF ACTUAL PRODUCT

Display of Actual Product (Labeling Example)



*1 Display name of actual product : 2 1 3 1

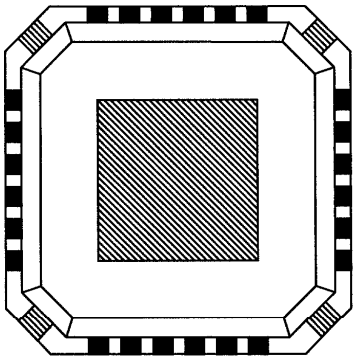
*2 Weekly Code : 9 0 1 K A

- Toshiba's internal management code
- 1st week
- Year (last digit)

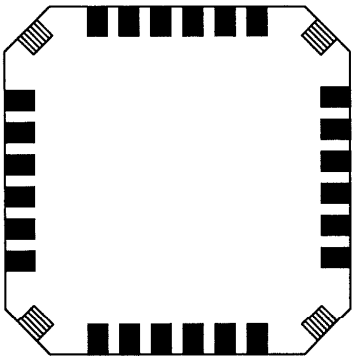
REQUESTS CONCERNING USE OF QON

Outline Drawing of Package

(Upper Surface)



(Lower Surface)



When using QON, please take into account the following items.

(1) Do not carry out soldering on the island section in the four corners of the package (the section shown on the lower surface drawing with diagonal lines) with the aim of increasing mechanical strength.

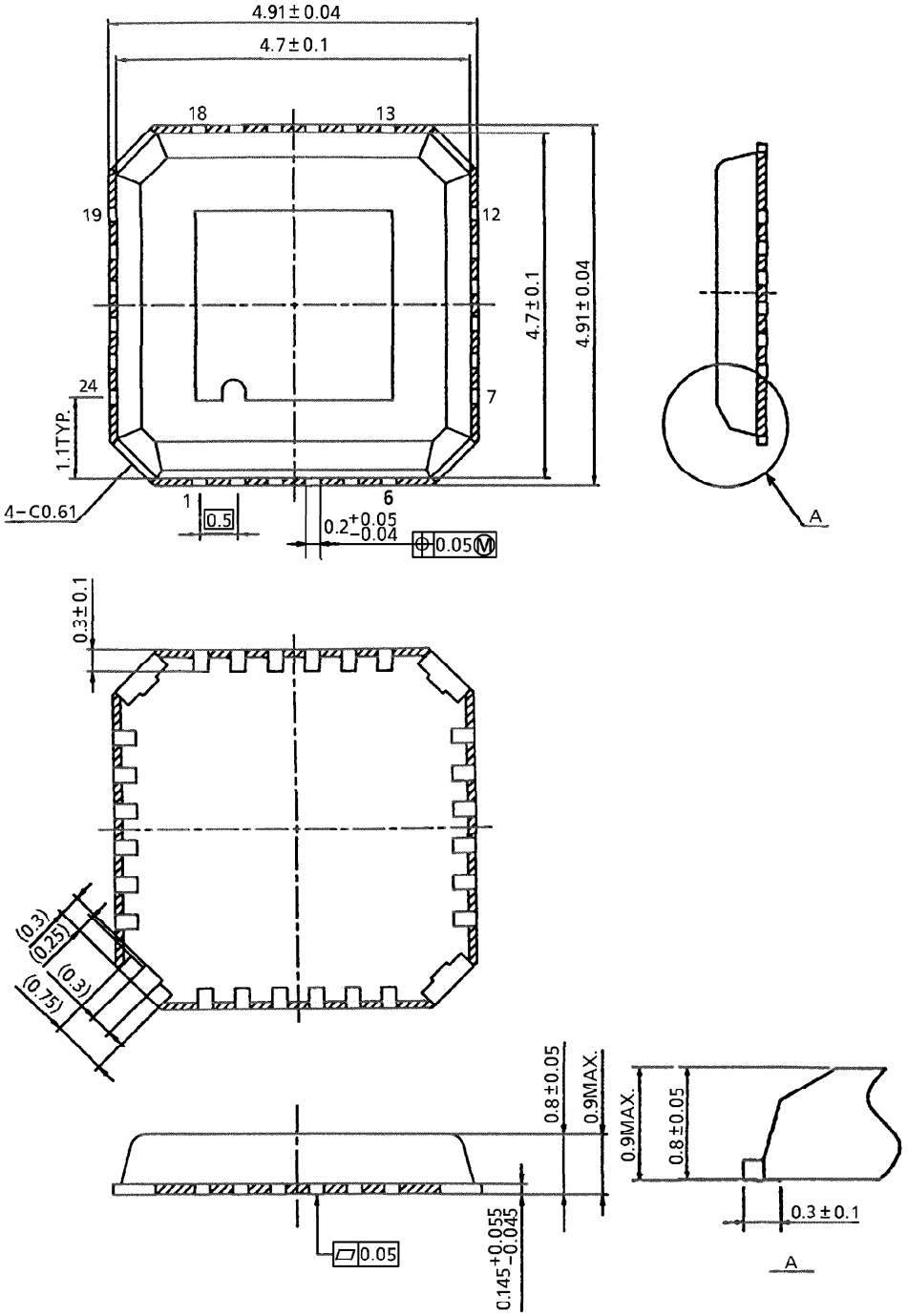
(2) The island section exposed on the package surface (the section shown on the upper surface drawing with diagonal lines) must be used as *1 below while electrically insulated from outside.

*1 : Ensure that the island section (the section shown on the lower surface drawing with diagonal lines) does not come into contact with solder from through-holes on the board layout.

- When mounting or soldering, take care to ensure that neither static electricity nor electrical overstress is applied to the IC (measures to prevent anti-static, leaks, etc.).
- When incorporating into a set, adopt a set design that does not apply voltage directly to the island section.

OUTLINE DRAWING

QON24-P-0505-0.50 Unit : mm



Weight : 0.05 g (Typ.)